— Information for board assembly —

Package : SSOP5

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1. Construction and materials

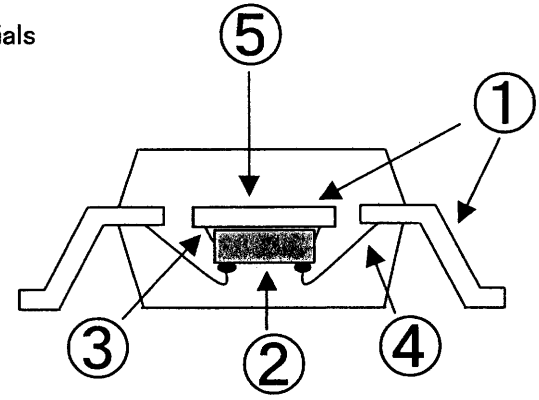


Fig. 1 Construction

No.	Name	Materials
①	Leadframe	Cu-Alloy (External lead : Solder plating)
②	Die	Silicone
③	Die attach	Ag paste
④	Wire	Au wire
⑤	Molding	Epoxy resin

The dryness weight : 14mg

2. Packing specification

2. 1. Packing forms、Packing quantities、Packing directions

Packing forms	Embossed tape
Packing quantities	3000pcs／reel
Packing directions	TR (When you keep a reel in your left hand and draw out a tape by your right hand, 1PIN is upper right.)

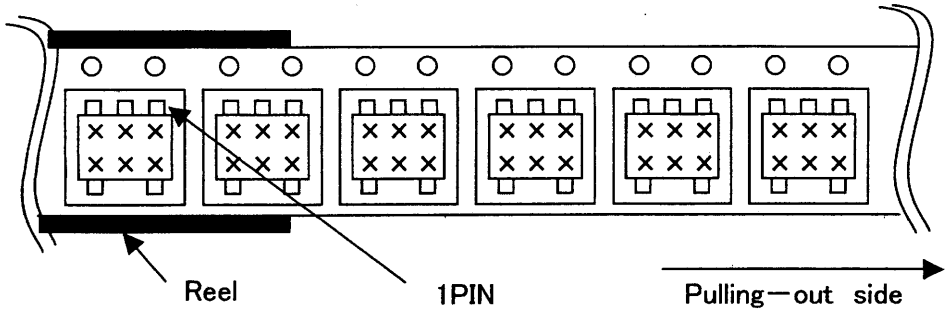


Fig. 2 Packing directions

2. 2. Embossed tape and Reel dimension
2. 2. 1. Embossed tape dimension

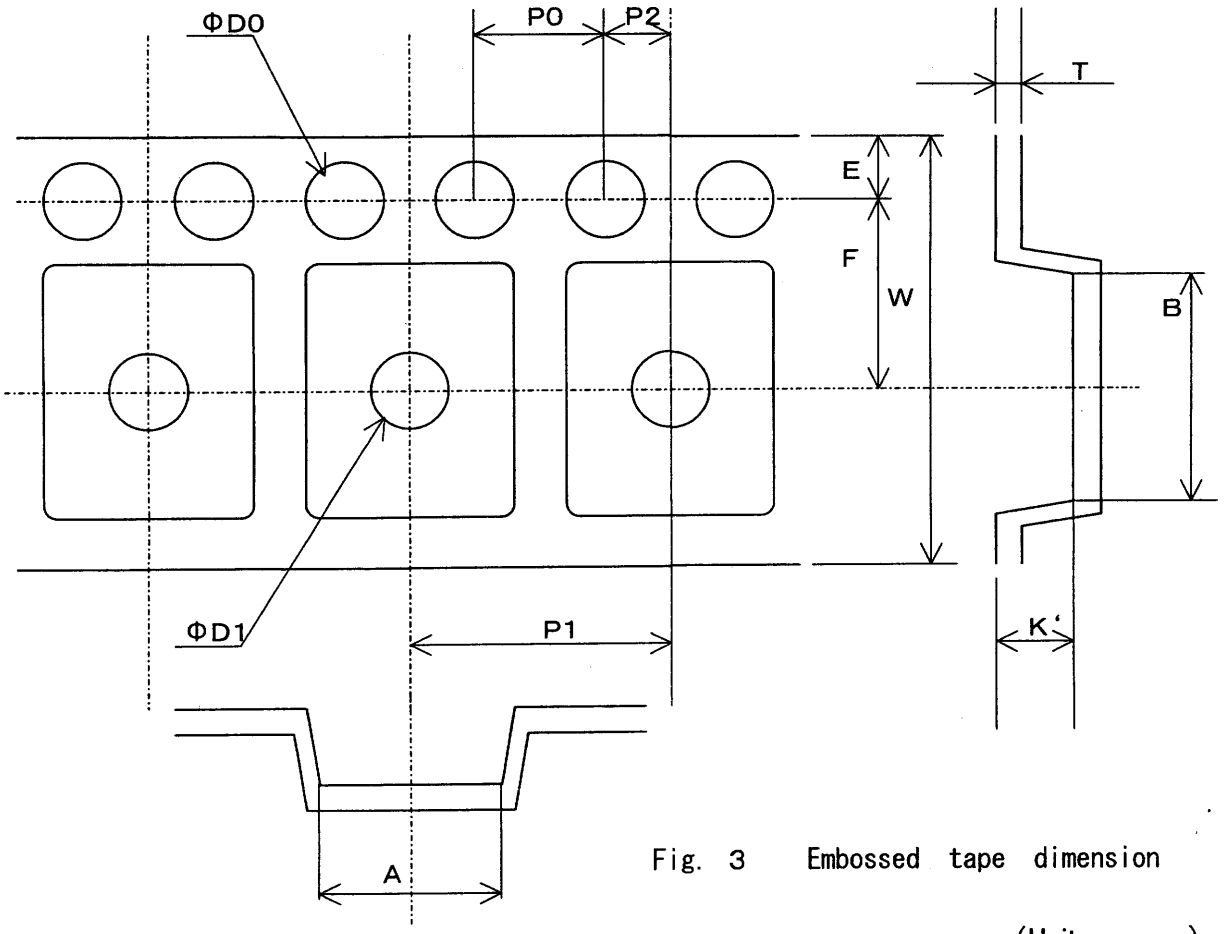


Fig. 3 Embossed tape dimension

(Unit : mm)

A	B	D0	D1	E	F	K'	P0	P1	P2	T	W
3.2 ±0.1	3.1 ±0.1	Φ1.5 +0.1 −0	Φ1.1 ±0.1	1.75 ±0.1	3.5 ±0.05	1.3 ±0.2	4.0 ±0.1	4.0 ±0.1	2.0 ±0.05	0.3 ±0.1	8.0 ±0.2

2. 2. 1. Reel dimension

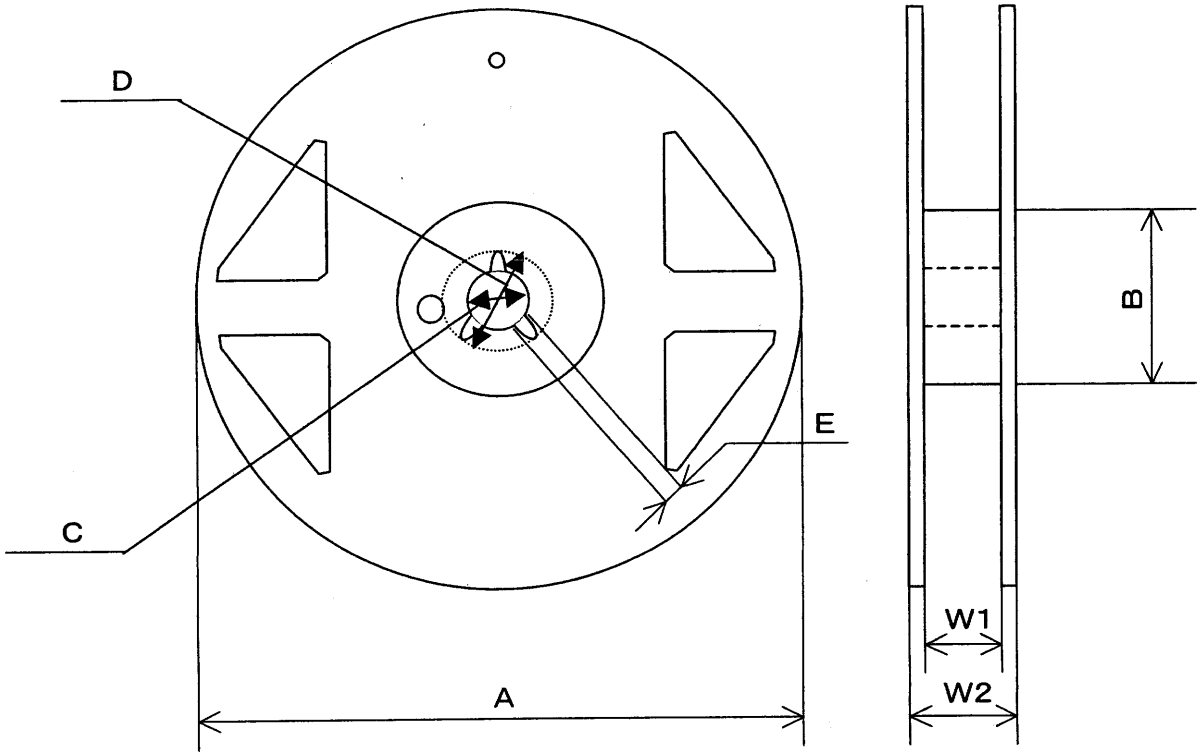


Fig. 4 Reel dimension

(Unit:mm)

A	B	C	D	E	W1	W2
Φ180 MAX	Φ50 MIN	Φ13.0 ±0.5	Φ20.2 MIN	1.5 MIN	10.0 ±1.0	16.0 MAX

2. 3. Leader tape and Trail tape specification

2. 3. 1. Leader tape specification

Leader tape has emptiness part which has no products over 40 pocket.

2. 3. 2. Trail tape specification

Trail tape has emptiness part which has no products over 10 pocket.

Trail tape isn't fixed directly to reel.

2. 4. Label marking

Sticking a label which records Fig. 5 to a reel and unit box.

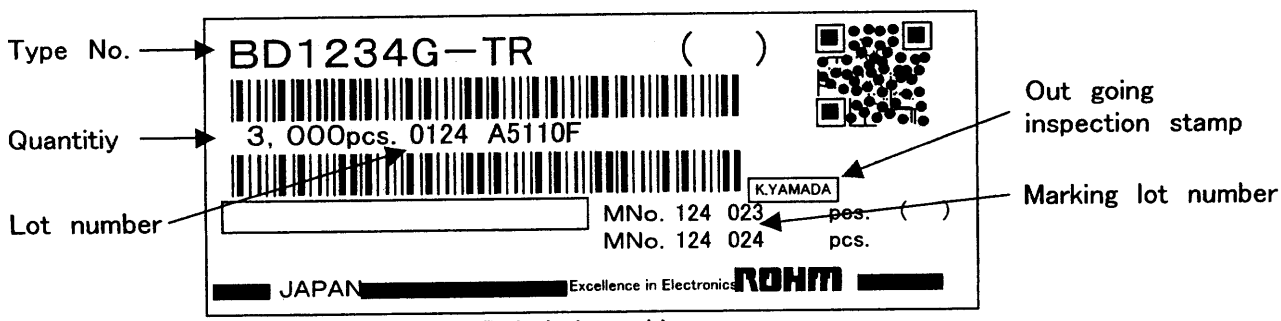


Fig. 5 Label marking

2. 5. Packing method

4reels in the unit box

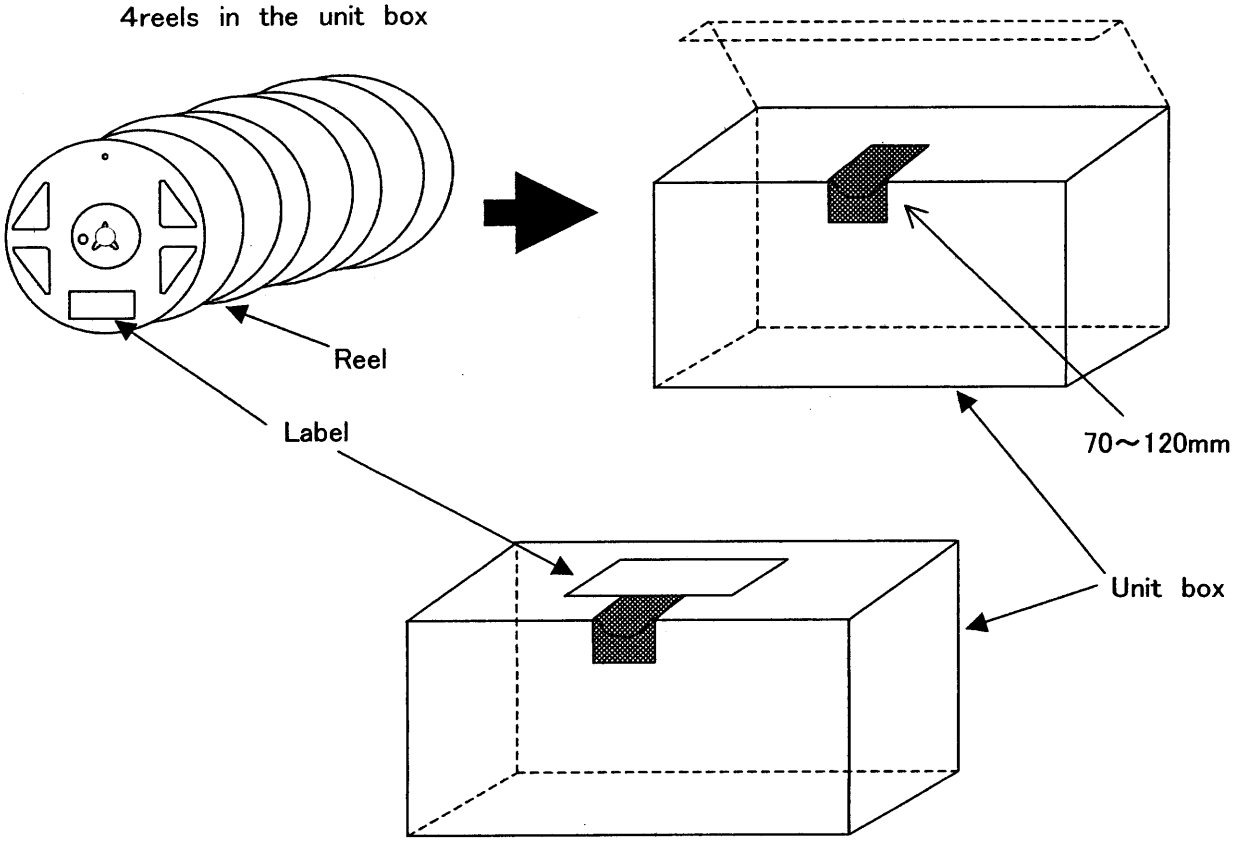


Fig. 6 Packing method

2. 6. Packing forms

The packing box is the dimension of Fig. 7.
The packing box can accommodate MAX 4 unit boxes.

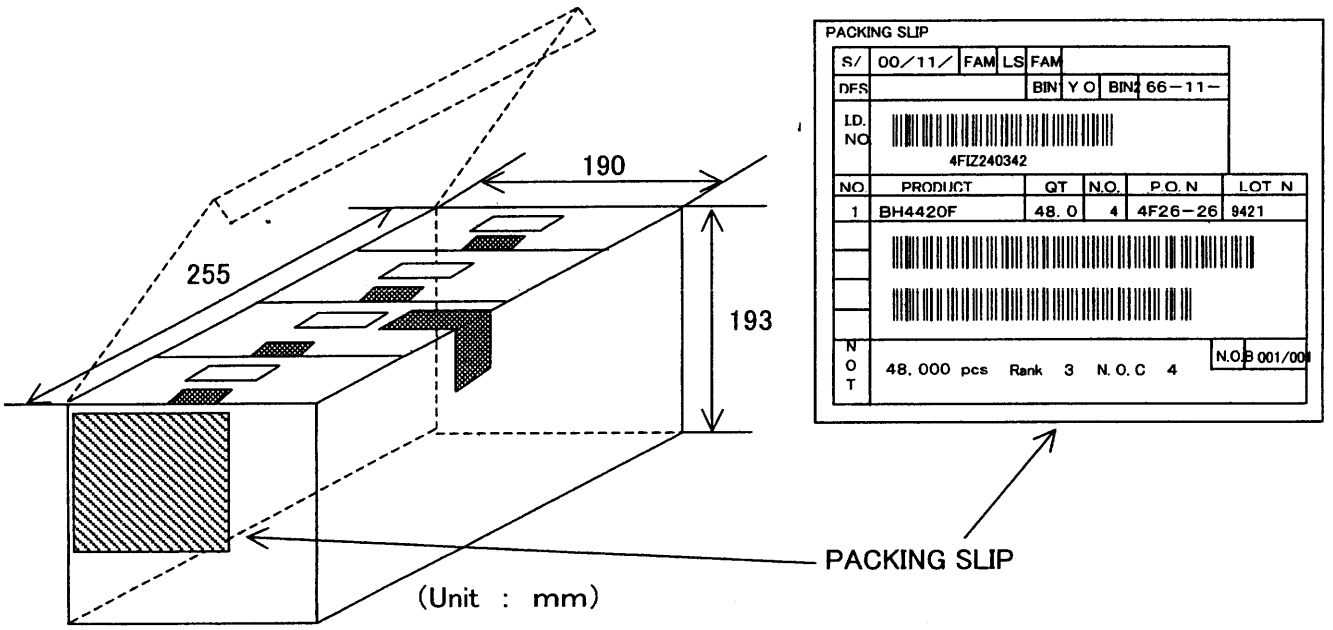


Fig. 7 Packing forms

2. 6. Packing materials

Material name	Material
Embossed tape	PS
Cover tape	PET + PE
Reel	PS
Desiccant	Silica gel
Unit box	Corrugated paper
Packing box	Corrugated paper

2. 7. Others

2. 7. 1. Peeling force of cover tape

The peeling force of the cover tape is spesified as 0. 2～0. 7N.

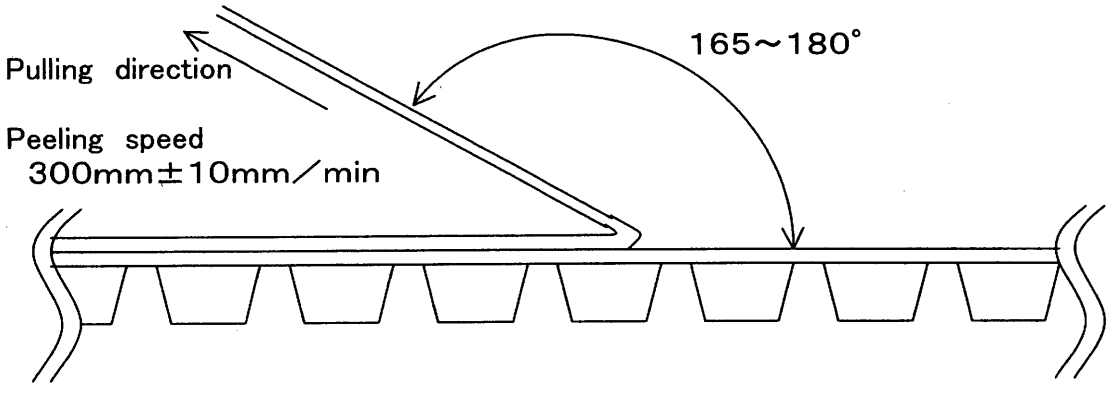


Fig. 8 Peeling method

2. 7. 2. Missing of taping devices

(1) Continuous missing is zero.

(1) Uncontinuous missing is MAX0. 1%／1reel.

3. Recommend soldring conditions

3. 1. Recommend dip soldering conditions

3. 1. 1. Flux and cleaning recommended condition

3. 1. 1. 1 Flux (Chlorine under 0. 2wt%)

Rosin flux with small content of chlorine

3. 1. 1. 2. Ultrasonic cleaning condition

Frequency : 28kHz

Ultrasonic wave output : MAX15W/liter

Solvent : Alcohole solvent (not containing chlorine)

Time : Within30sec (within 3min when ultrasonic wave is not used)

Solution temperatuer : MAX40℃

<Notices>

- Device must not be resonated.
- The device or print circuit board must not directly contact to the vibration source.
- Do not rub the mark surface with brush or fingers during cleaning or when cleaning solvent attaches to the device.
- Respecting decision to protect the ozone layer, our company dose not recommend cleaning with fleon or chlorine solvent. (1.1.1-trichloroethane) Quality and reliability of the product will not be decreased if the recommended cleaning conditions are controlled and maintained.

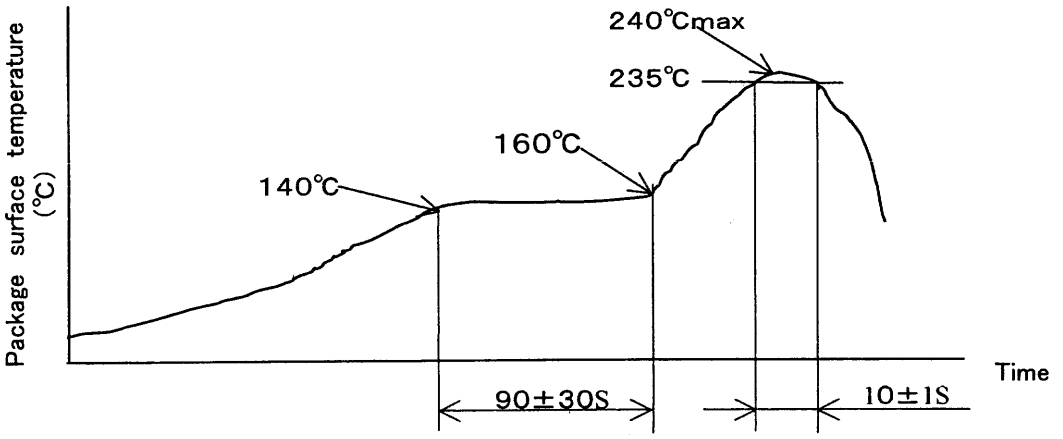
3. 1. 2. Soldering dip condition

Processing	Conditions	
	Temperature	Time
Pre-heating	100±20℃	10～30sec
Solder bath	MAX260℃	Within10sec

3. 1. 3. Notes when the product is mounted by dip soldering.

- Please do not use other soldering methods when dip soldering is used.
- Please wash off flux residue completely after dip soldering due to the influence on the reliability of the other parts or board wiring.
- Condition when partial heat supply method (by soldering iron) is used; 350℃MAX、3secMAX/pin

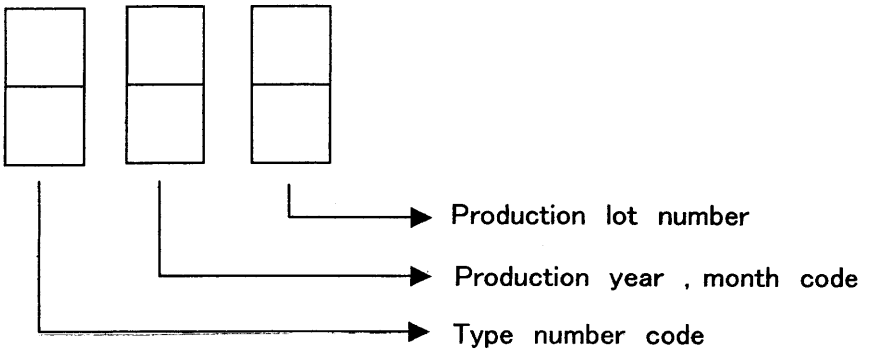
3. 2. Infrance radiation reflow condition



<Notice>

Additional heat is until 2－times.

4. Meaning of marking lot number



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